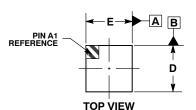
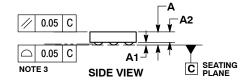
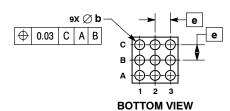


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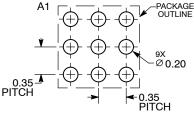
DATE 12 FEB 2018







RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- CONTROLLING DIMENSION: MILLIMETERS.
 COPLANARITY APPLIES TO THE SPHERICAL
 CROWNS OF THE SOLDER BALLS.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α			0.33	
A1	0.04	0.06	0.08	
A2	0.23 REF			
b	0.180	0.200	0.220	
D	0.99	1.02	1.05	
E	0.99	1.02	1.05	
e	0.35 BSC			

GENERIC MARKING DIAGRAM*



= Assembly Location

= Year

W = Work Week

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present. Some products may not follow the Generic Marking.

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